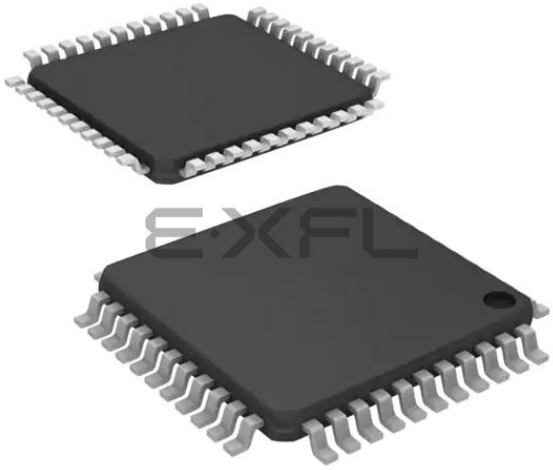


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

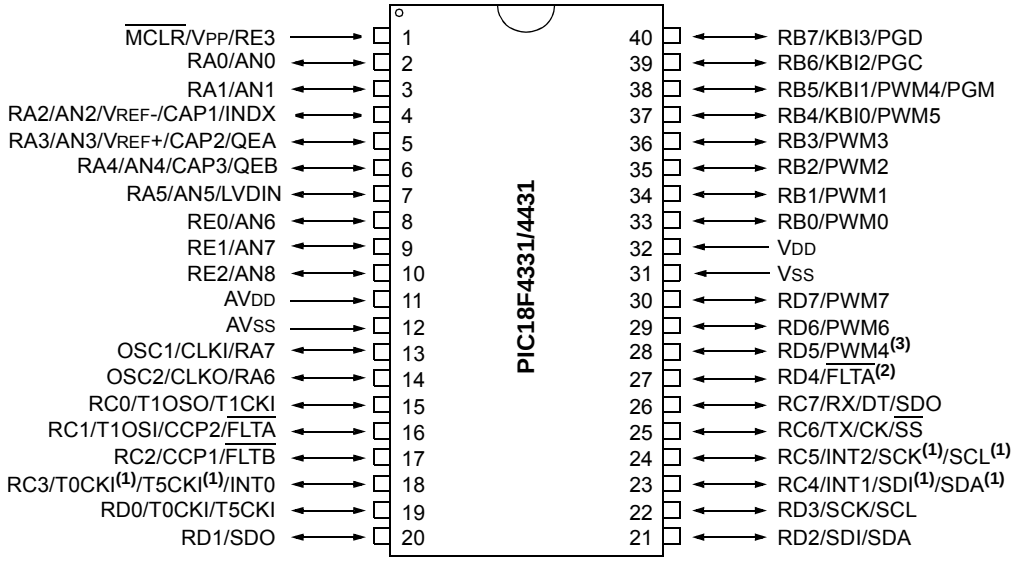
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, Power Control PWM, QEI, POR, PWM, WDT
Number of I/O	36
Program Memory Size	8KB (4K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 9x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f4331t-i-pt

Pin Diagrams (Continued)

40-Pin PDIP



Note 1: RC3 is the alternate pin for T0CKI/T5CKI; RC4 is the alternate pin for SDI/SDA; RC5 is the alternate pin for SCK/SCL.

2: RD4 is the alternate pin for FLTA.

3: RD5 is the alternate pin for PWM4.

TABLE 1-3: PIC18F4331/4431 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	TQFP	QFN			
						PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0/PWM0	33	8	9			
RB0				I/O	TTL	Digital I/O.
PWM0				O	TTL	PWM Output 0.
RB1/PWM1	34	9	10			
RB1				I/O	TTL	Digital I/O.
PWM1				O	TTL	PWM Output 1.
RB2/PWM2	35	10	11			
RB2				I/O	TTL	Digital I/O.
PWM2				O	TTL	PWM Output 2.
RB3/PWM3	36	11	12			
RB3				I/O	TTL	Digital I/O.
PWM3				O	TTL	PWM Output 3.
RB4/KBI0/PWM5	37	14	14			
RB4				I/O	TTL	Digital I/O.
KBI0				I	TTL	Interrupt-on-change pin.
PWM5				O	TTL	PWM Output 5.
RB5/KBI1/PWM4/ PGM	38	15	15			
RB5				I/O	TTL	Digital I/O.
KBI1				I	TTL	Interrupt-on-change pin.
PWM4				O	TTL	PWM Output 4.
PGM				I/O	ST	Single-Supply ICSP™ Programming entry pin.
RB6/KBI2/PGC	39	16	16			
RB6				I/O	TTL	Digital I/O.
KBI2				I	TTL	Interrupt-on-change pin.
PGC				I/O	ST	In-Circuit Debugger and ICSP programming clock pin.
RB7/KBI3/PGD	40	17	17			
RB7				I/O	TTL	Digital I/O.
KBI3				I	TTL	Interrupt-on-change pin.
PGD				I/O	ST	In-Circuit Debugger and ICSP programming data pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: RC3 is the alternate pin for T0CKI/T5CKI; RC4 is the alternate pin for SDI/SDA; RC5 is the alternate pin for SCK/SCL; RC7 is the alternate pin for SDO.

2: RD4 is the alternate pin for $\overline{\text{FLTA}}$.

3: RD5 is the alternate pin for PWM4.

2.0 GUIDELINES FOR GETTING STARTED WITH PIC18F MICROCONTROLLERS

2.1 Basic Connection Requirements

Getting started with the PIC18F2331/2431/4331/4431 family of 8-bit microcontrollers requires attention to a minimal set of device pin connections before proceeding with development.

The following pins must always be connected:

- All VDD and VSS pins
  (see **Section 2.2 "Power Supply Pins"**)
- All AVDD and AVSS pins, regardless of whether or not the analog device features are used
  (see **Section 2.2 "Power Supply Pins"**)
- $\overline{\text{MCLR}}$ pin
  (see **Section 2.3 "Master Clear (MCLR) Pin"**)

These pins must also be connected if they are being used in the end application:

- PGC/PGD pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes
  (see **Section 2.4 "ICSP Pins"**)
- OSCI and OSCO pins when an external oscillator source is used
  (see **Section 2.5 "External Oscillator Pins"**)

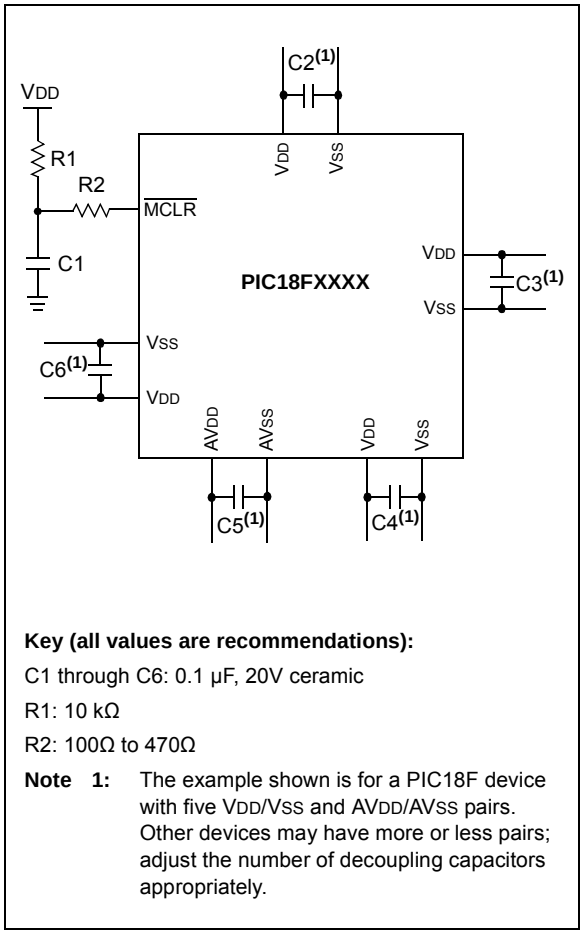
Additionally, the following pins may be required:

- VREF+/VREF- pins are used when external voltage reference for analog modules is implemented

Note:	The AVDD and AVSS pins must always be connected, regardless of whether any of the analog modules are being used.

The minimum mandatory connections are shown in Figure 2-1.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTIONS



Key (all values are recommendations):

C1 through C6: 0.1 µF, 20V ceramic

R1: 10 kΩ

R2: 100Ω to 470Ω

Note 1: The example shown is for a PIC18F device with five VDD/VSS and AVDD/AVSS pairs. Other devices may have more or less pairs; adjust the number of decoupling capacitors appropriately.

2.2 Power Supply Pins

2.2.1 DECOUPLING CAPACITORS

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS, is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A 0.1 μF (100 nF), 10-20V capacitor is recommended. The capacitor should be a low-ESR device, with a resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μF to 0.001 μF. Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1 μF in parallel with 0.001 μF).
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

2.2.2 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits, including microcontrollers, to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 μF to 47 μF.

2.2.3 CONSIDERATIONS WHEN USING BOR

When the Brown-out Reset (BOR) feature is enabled, a sudden change in VDD may result in a spontaneous BOR event. This can happen when the microcontroller is operating under normal operating conditions, regardless of what the BOR set point has been programmed to, and even if VDD does not approach the set point. The precipitating factor in these BOR events is a rise or fall in VDD with a slew rate faster than 0.15V/μs.

An application that incorporates adequate decoupling between the power supplies will not experience such rapid voltage changes. Additionally, the use of an electrolytic tank capacitor across VDD and VSS, as described above, will be helpful in preventing high slew rate transitions.

If the application has components that turn on or off, and share the same VDD circuit as the microcontroller, the BOR can be disabled in software by using the SBOREN bit before switching the component. Afterwards, allow a small delay before re-enabling the BOR. By doing this, it is ensured that the BOR is disabled during the interval that might cause high slew rate changes of VDD.

Note:	Not all devices incorporate software BOR control. See **Section 5.0 "Reset"** for device-specific information.

NOTES:

TABLE 6-2: REGISTER FILE SUMMARY (PIC18F2331/2431/4331/4431)

File Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR
TOSU	—	—	—	Top-of-Stack Upper Byte (TOS<20:16>)					---0 0000
TOSH	Top-of-Stack High Byte (TOS<15:8>)								0000 0000
TOSL	Top-of-Stack Low Byte (TOS<7:0>)								0000 0000
STKPTR	STKFUL	STKUNF	—	SP4	SP3	SP2	SP1	SP0	00-0 0000
PCLATU	—	—	bit 21(3)	Holding Register for PC<20:16>					---0 0000
PCLATH	Holding Register for PC<15:8>								0000 0000
PCL	PC Low Byte (PC<7:0>)								0000 0000
TBLPTRU	—	—	bit 21(3)	Program Memory Table Pointer Upper Byte (TBLPTR<20:16>)					--00 0000
TBLPTRH	Program Memory Table Pointer High Byte (TBLPTR<15:8>)								0000 0000
TBLPTRL	Program Memory Table Pointer Low Byte (TBLPTR<7:0>)								0000 0000
TABLAT	Program Memory Table Latch								0000 0000
PRODH	Product Register High Byte								xxxx xxxx
PRODL	Product Register Low Byte								xxxx xxxx
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x
INTCON2	$\overline{\text{RBPU}}$	INTEDG0	INTEDG1	INTEDG2	—	TMR0IP	—	RBIP	1111 -1-1
INTCON3	INT2IP	INT1IP	—	INT2IE	INT1IE	—	INT2IF	INT1IF	11-0 0-00
INDF0	Uses contents of FSR0 to address data memory – value of FSR0 not changed (not a physical register)								N/A
POSTINC0	Uses contents of FSR0 to address data memory – value of FSR0 post-incremented (not a physical register)								N/A
POSTDEC0	Uses contents of FSR0 to address data memory – value of FSR0 post-decremented (not a physical register)								N/A
PREINC0	Uses contents of FSR0 to address data memory – value of FSR0 pre-incremented (not a physical register)								N/A
PLUSW0	Uses contents of FSR0 to address data memory – value of FSR0 offset by W (not a physical register)								N/A
FSR0H	—	—	—	—	Indirect Data Memory Address Pointer 0 High				---- xxxx
FSR0L	Indirect Data Memory Address Pointer 0 Low Byte								xxxx xxxx
WREG	Working Register								xxxx xxxx
INDF1	Uses contents of FSR1 to address data memory – value of FSR1 not changed (not a physical register)								N/A
POSTINC1	Uses contents of FSR1 to address data memory – value of FSR1 post-incremented (not a physical register)								N/A
POSTDEC1	Uses contents of FSR1 to address data memory – value of FSR1 post-decremented (not a physical register)								N/A
PREINC1	Uses contents of FSR1 to address data memory – value of FSR1 pre-incremented (not a physical register)								N/A
PLUSW1	Uses contents of FSR1 to address data memory – value of FSR1 offset by W (not a physical register)								N/A
FSR1H	—	—	—	—	Indirect Data Memory Address Pointer 1 High Byte				---- 0000
FSR1L	Indirect Data Memory Address Pointer 1 Low Byte								xxxx xxxx
BSR	—	—	—	—	Bank Select Register				---- 0000
INDF2	Uses contents of FSR2 to address data memory – value of FSR2 not changed (not a physical register)								N/A
POSTINC2	Uses contents of FSR2 to address data memory – value of FSR2 post-incremented (not a physical register)								N/A
POSTDEC2	Uses contents of FSR2 to address data memory – value of FSR2 post-decremented (not a physical register)								N/A
PREINC2	Uses contents of FSR2 to address data memory – value of FSR2 pre-incremented (not a physical register)								N/A
PLUSW2	Uses contents of FSR2 to address data memory – value of FSR2 offset by W (not a physical register)								N/A
FSR2H	—	—	—	—	Indirect Data Memory Address Pointer 2 High Byte				---- 0000
FSR2L	Indirect Data Memory Address Pointer 2 Low Byte								xxxx xxxx
STATUS	—	—	—	N	OV	Z	DC	C	---x xxxx
TMR0H	Timer0 Register High Byte								0000 0000
TMR0L	Timer0 Register Low Byte								xxxx xxxx
T0CON	TMR0ON	T016BIT	T0CS	T0SE	PSA	T0PS2	T0PS1	T0PS0	1111 1111

Legend: x = unknown, u = unchanged, - = unimplemented, q = value depends on condition. Shaded cells are unimplemented.

Note 1: RA6 and associated bits are configured as port pins in RCIO, ECIO and INTIO2 (with port function on RA6) Oscillator modes only and read '0' in all other oscillator modes.

2: RA7 and associated bits are configured as port pins in INTIO2 Oscillator mode only and read '0' in all other modes.

3: Bit 21 of the PC is only available in Test mode and Serial Programming modes.

4: These registers and/or bits are not implemented on the PIC18F2331/2431 devices and read as '0'.

5: The RE3 port bit is only available for PIC18F4331/4431 devices when the MCLRE fuse (CONFIG3H<7>) is programmed to '0'; otherwise, RE3 reads '0'. This bit is read-only.

7.3 Reading the Data EEPROM Memory

To read a data memory location, the user must write the address to the EEADR register, clear the EEPGD control bit (EECON1<7>) and then set control bit, RD (EECON1<0>). The data is available for the very next instruction cycle; therefore, the EEDATA register can be read by the next instruction. EEDATA will hold this value until another read operation, or until it is written to by the user (during a write operation).The basic process is shown in Example 7-1.

7.4 Writing to the Data EEPROM Memory

To write an EEPROM data location, the address must first be written to the EEADR register and the data written to the EEDATA register. The sequence in Example 7-2 must be followed to initiate the write cycle.

The write will not begin if this sequence is not exactly followed (write 55h to EECON2, write 0AAh to EECON2, then set WR bit) for each byte. It is strongly recommended that interrupts be disabled during this code segment.

Additionally, the WREN bit in EECON1 must be set to enable writes. This mechanism prevents accidental writes to data EEPROM due to unexpected code execution (i.e., runaway programs). The WREN bit should be kept clear at all times, except when updating the EEPROM. The WREN bit is not cleared by hardware.

After a write sequence has been initiated, EECON1, EEADR and EEDATA cannot be modified. The WR bit will be inhibited from being set unless the WREN bit is set. The WREN bit must be set on a previous instruction. Both WR and WREN cannot be set with the same instruction.

At the completion of the write cycle, the WR bit is cleared in hardware and the EEPROM Interrupt Flag bit (EEIF) is set. The user may either enable this interrupt or poll this bit. EEIF must be cleared by software.

7.5 Write Verify

Depending on the application, good programming practice may dictate that the value written to the memory should be verified against the original value. This should be used in applications where excessive writes can stress bits near the specification limit.

7.6 Protection Against Spurious Write

There are conditions when the device may not want to write to the data EEPROM memory. To protect against spurious EEPROM writes, various mechanisms have been built-in. On power-up, the WREN bit is cleared. Also, the Power-up Timer (72 ms duration) prevents EEPROM write.

The write initiate sequence and the WREN bit together help prevent an accidental write during brown-out, power glitch, or software malfunction.

EXAMPLE 7-1: DATA EEPROM READ

```
        MOVLW   DATA_EE_ADDR      ;
        MOVWF   EEADR             ; Data Memory Address to read
        BCF     EECON1, EEPGD     ; Point to DATA memory
        BSF     EECON1, RD        ; EEPROM Read
        MOVF    EEDATA, W         ; W = EEDATA
```

EXAMPLE 7-2: DATA EEPROM WRITE

```
                MOVLW   DATA_EE_ADDR      ;
                MOVWF   EEADR             ; Data Memory Address to write
                MOVLW   DATA_EE_DATA      ;
                MOVWF   EEDATA            ; Data Memory Value to write
                BCF     EECON1, EEPGD     ; Point to DATA memory
                BCF     EECON1, CFGS      ; Access EEPROM
                BSF     EECON1, WREN      ; Enable writes
                BCF     INTCON, GIE       ; Disable Interrupts
                MOVLW   55h               ;
Required        MOVWF   EECON2            ; Write 55h
Sequence        MOVLW   0AAh              ;
                MOVWF   EECON2            ; Write 0AAh
                BSF     EECON1, WR        ; Set WR bit to begin write
                BTFSC   EECON1, WR        ; Wait for write to complete

                GOTO    $-2               ;
                BSF     INTCON, GIE       ; Enable interrupts
```

8.5.1 FLASH PROGRAM MEMORY WRITE SEQUENCE

The sequence of events for programming an internal program memory location should be:

1. Read 64 bytes into RAM.
2. Update data values in RAM as necessary.
3. Load Table Pointer with address being erased.
4. Do the row erase procedure (see **Section 8.4.1 "Flash Program Memory Erase Sequence"**).
5. Load Table Pointer with the address of the first byte being written.
6. Write the first 8 bytes into the holding registers with auto-increment.
7. Set the EECON1 register for the write operation by doing the following:
   - Set the EEPGD bit to point to program memory
   - Clear the CFGS bit to access program memory
   - Set the WREN bit to enable byte writes
8. Disable interrupts.
9. Write 55h to EECON2.
10. Write 0AAh to EECON2.
11. Set the WR bit. This will begin the write cycle.
12. The CPU will stall for the duration of the write (about 2 ms using internal timer).
13. Execute a NOP.
14. Re-enable interrupts.
15. Repeat Steps 6-14 seven times to write 64 bytes.
16. Verify the memory (table read).

This procedure will require about 18 ms to update one row of 64 bytes of memory. An example of the required code is given in Example 8-3.

10.1 INTCON Registers

The INTCON registers are readable and writable registers which contain various enable, priority and flag bits.

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt. This feature allows for software polling.

REGISTER 10-1: INTCON: INTERRUPT CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **GIE/GIEH:** Global Interrupt Enable bit
When IPEN = 0:
1 = Enables all unmasked interrupts
0 = Disables all interrupts
When IPEN = 1:
1 = Enables all high-priority interrupts
0 = Disables all high-priority interrupts

bit 6 **PEIE/GIEL:** Peripheral Interrupt Enable bit
When IPEN = 0:
1 = Enables all unmasked peripheral interrupts
0 = Disables all peripheral interrupts
When IPEN = 1:
1 = Enables all low-priority peripheral interrupts
0 = Disables all low-priority peripheral interrupts

bit 5 **TMR0IE:** TMR0 Overflow Interrupt Enable bit
1 = Enables the TMR0 overflow interrupt
0 = Disables the TMR0 overflow interrupt

bit 4 **INT0IE:** INT0 External Interrupt Enable bit
1 = Enables the INT0 external interrupt
0 = Disables the INT0 external interrupt

bit 3 **RBIE:** RB Port Change Interrupt Enable bit
1 = Enables the RB port change interrupt for RB<7:4> pins
0 = Disables the RB port change interrupt for RB<7:4> pins

bit 2 **TMR0IF:** TMR0 Overflow Interrupt Flag bit
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow

bit 1 **INT0IF:** INT0 External Interrupt Flag bit
1 = The INT0 external interrupt occurred (must be cleared in software)
0 = The INT0 external interrupt did not occur

bit 0 **RBIF:** RB Port Change Interrupt Flag bit
1 = At least one of the RB<7:4> pins changed state (must be cleared in software)
0 = None of the RB<7:4> pins have changed state

REGISTER 10-6: PIR3: PERIPHERAL INTERRUPT REQUEST (FLAG) REGISTER 3

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	PTIF	IC3DRIF	IC2QEIF	IC1IF	TMR5IF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **PTIF:** PWM Time Base Interrupt bit
- 1 = PWM time base matched the value in the PTPER registers. Interrupt is issued according to the postscaler settings. PTIF must be cleared in software.
- 0 = PWM time base has not matched the value in the PTPER registers

bit 3 **IC3DRIF:** IC3 Interrupt Flag/Direction Change Interrupt Flag bit

IC3 Enabled (CAP3CON<3:0>):
- 1 = TMR5 value was captured by the active edge on CAP3 input (must be cleared in software)
- 0 = TMR5 capture has not occurred

QEI Enabled (QEIM<2:0>):
- 1 = Direction of rotation has changed (must be cleared in software)
- 0 = Direction of rotation has not changed

bit 2 **IC2QEIF:** IC2 Interrupt Flag/QEI Interrupt Flag bit

IC2 Enabled (CAP2CON<3:0>):
- 1 = TMR5 value was captured by the active edge on CAP2 input (must be cleared in software)
- 0 = TMR5 capture has not occurred

QEI Enabled (QEIM<2:0>):
- 1 = The QEI position counter has reached the MAXCNT value, or the index pulse, INDX, has been detected. Depends on the QEI operating mode enabled. Must be cleared in software.
- 0 = The QEI position counter has not reached the MAXCNT value or the index pulse has not been detected

bit 1 IC1 Enabled (CAP1CON<3:0>):
- 1 = TMR5 value was captured by the active edge on CAP1 input (must be cleared in software)
- 0 = TMR5 capture has not occurred

QEI Enabled (QEIM<2:0>), Velocity Measurement Mode Enabled ($\overline{\text{VELM}}$ = 0 in QEICON register):
- 1 = Timer5 value was captured by the active velocity edge (based on PHA or PHB input). CAP1REN bit must be set in CAP1CON register. IC1IF must be cleared in software.
- 0 = Timer5 value was not captured by the active velocity edge

bit 0 **TMR5IF:** Timer5 Interrupt Flag bit
- 1 = Timer5 time base matched the PR5 value (must be cleared in software)
- 0 = Timer5 time base did not match the PR5 value

NOTES:

17.2 Quadrature Encoder Interface

The Quadrature Encoder Interface (QEI) decodes speed and motion sensor information. It can be used in any application that uses a quadrature encoder for feedback. The interface implements these features:

- Three QEI inputs: two phase signals (QEA and QEB) and one index signal (INDX)
- Direction of movement detection with a direction change interrupt (IC3DRIF)
- 16-bit up/down position counter
- Standard and High-Precision Position Tracking modes
- Two Position Update modes (x2 and x4)
- Velocity measurement with a programmable postscaler for high-speed velocity measurement
- Position counter interrupt (IC2QEIF in the PIR3 register)
- Velocity control interrupt (IC1IF in the PIR3 register)

The QEI submodule has three main components: the QEI control logic block, the position counter and velocity postscaler.

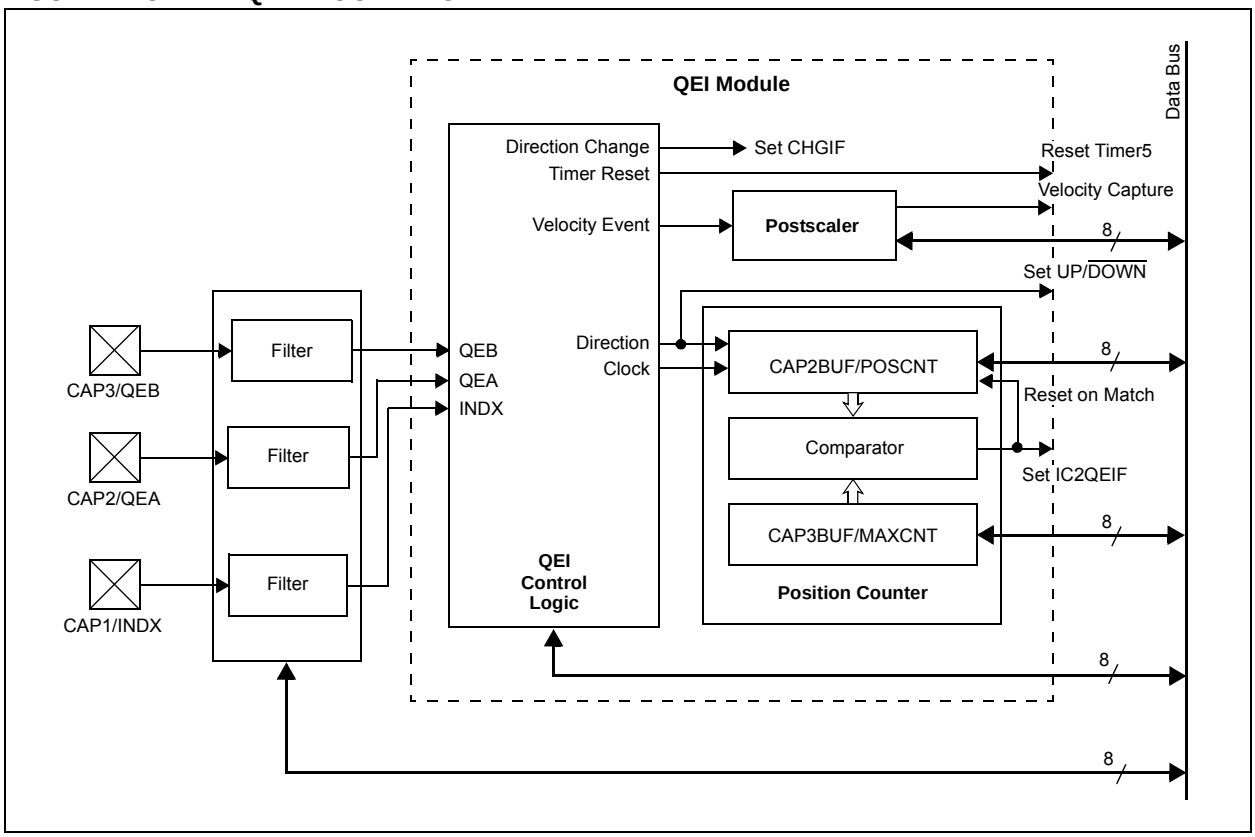
The QEI control logic detects the leading edge on the QEA or QEB phase input pins and generates the count pulse, which is sent to the position counter logic. It also samples the index input signal (INDX) and generates the direction of the rotation signal (up/down) and the velocity event signals.

The position counter acts as an integrator for tracking distance traveled. The QEA and QEB input edges serve as the stimulus to create the input clock which advances the Position Counter register (POSCNT). The register is incremented on either the QEA input edge, or the QEA and QEB input edges, depending on the operating mode. It is reset either by a rollover on match to the Period register, MAXCNT, or on the external index pulse input signal (INDX). An interrupt is generated on a Reset of POSCNT if the position counter interrupt is enabled.

The velocity postscaler down samples the velocity pulses used to increment the velocity counter by a specified ratio. It essentially divides down the number of velocity pulses to one output per so many inputs, preserving the pulse width in the process.

A simplified block-diagram of the QEI module is shown in Figure 17-8.

FIGURE 17-8: QEI BLOCK DIAGRAM



21.9 A/D Conversions

Figure 21-3 shows the operation of the A/D Converter after the GO/$\overline{\text{DONE}}$ bit has been set and the ACQT<2:0> bits are cleared. A conversion is started after the following instruction to allow entry into Sleep mode before the conversion begins. The internal A/D RC oscillator must be selected to perform a conversion in Sleep.

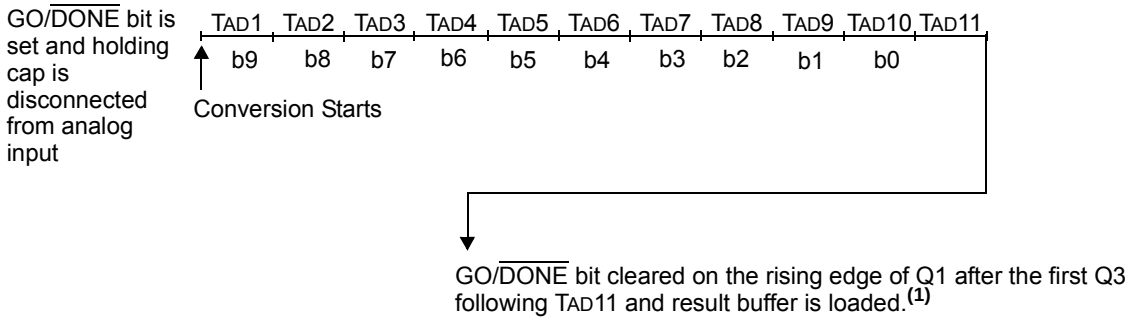
Figure 21-4 shows the operation of the A/D Converter after the GO/$\overline{\text{DONE}}$ bit has been set, the ACQT<3:0> bits are set to '010' and a 4 TAD acquisition time is selected before the conversion starts.

Clearing the GO/$\overline{\text{DONE}}$ bit during a conversion will abort the current conversion. The resulting buffer location will contain the partially completed A/D conversion sample. This will not set the ADIF flag, therefore, the user must read the buffer location before a conversion sequence overwrites it.

After the A/D conversion is completed or aborted, a 2 TAD wait is required before the next acquisition can be started. After this wait, acquisition on the selected channel is automatically started.

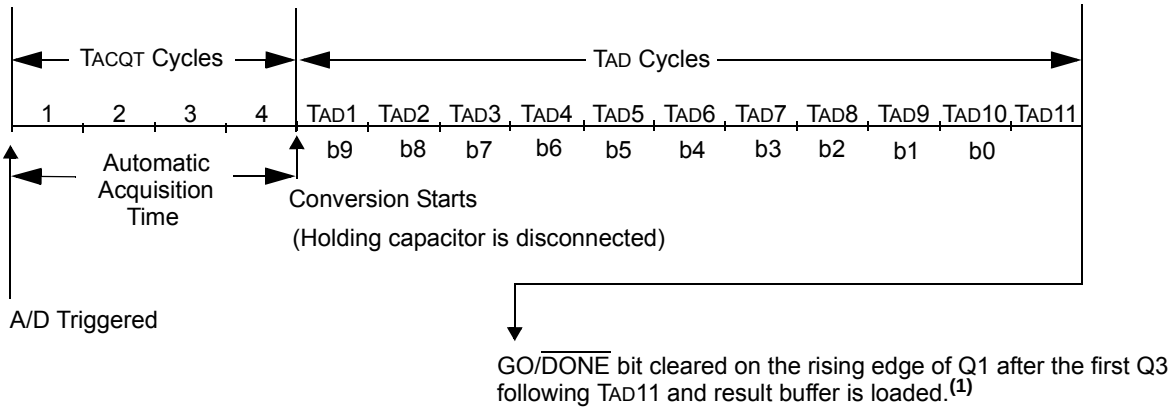
Note:	The GO/$\overline{\text{DONE}}$ bit should **NOT** be set in the same instruction that turns on the A/D.

FIGURE 21-3: A/D CONVERSION TAD CYCLES (ACQT<2:0> = 000, TACQ = 0)



Note 1: Conversion time is a minimum of 11 TAD + 2 TCY and a maximum of 11 TAD + 6 TCY.

FIGURE 21-4: A/D CONVERSION TAD CYCLES (ACQT<3:0> = 0010, TACQ = 4 TAD)



Note 1: In Continuous modes, next conversion starts at the end of TAD12.

REGISTER 23-9: CONFIG6L: CONFIGURATION REGISTER 6 LOW (BYTE ADDRESS 30000Ah)

U-0	U-0	U-0	U-0	R/P-1	R/P-1	R/P-1	R/P-1
—	—	—	—	WRT3(1,2)	WRT2(1,2)	WRT1(2)	WRT0(2)
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		U = Unchanged from programmed state

bit 7-4 **Unimplemented:** Read as '0'

bit 3 **WRT3:** Write Protection bit(1,2)
1 = Block 3 is not write-protected
0 = Block 3 is write-protected

bit 2 **WRT2:** Write Protection bit(1,2)
1 = Block 2 is not write-protected
0 = Block 2 is write-protected

bit 1 **WRT1:** Write Protection bit(2)
1 = Block 1 is not write-protected
0 = Block 1 is write-protected

bit 0 **WRT0:** Write Protection bit(2)
1 = Block 0 is not write-protected
0 = Block 0 is write-protected

Note 1: Unimplemented in PIC18F2331/4331 devices; maintain this bit set.
2: Refer to Figure 23-5 for block boundary addresses.

REGISTER 23-10: CONFIG6H: CONFIGURATION REGISTER 6 HIGH (BYTE ADDRESS 30000Bh)

R/P-1	R/P-1	R-1	U-0	U-0	U-0	U-0	U-0
WRTD(2)	WRTB(2)	WRTC(1,2)	—	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		U = Unchanged from programmed state

bit 7 **WRTD:** Data EEPROM Write Protection bit(2)
1 = Data EEPROM is not write-protected
0 = Data EEPROM is write-protected

bit 6 **WRTB:** Boot Block Write Protection bit(2)
1 = Boot block is not write-protected
0 = Boot block is write-protected

bit 5 **WRTC:** Configuration Register Write Protection bit(1,2)
1 = Configuration registers are not write-protected
0 = Configuration registers are write-protected

bit 4-0 **Unimplemented:** Read as '0'

Note 1: This bit is read-only in normal execution mode; it can be written only in Program mode.
2: Refer to Figure 23-5 for block boundary addresses.

BTG **Bit Toggle f**

Syntax: [*label*] BTG f,b[,a]

Operands: $0 \le f \le 255$
$0 \le b < 7$
$a \in [0,1]$

Operation: $(\overline{f<b>}) \rightarrow f<b>$

Status Affected: None

Encoding:

0111	bbba	ffff	ffff

Description: Bit 'b' in data memory location, 'f', is inverted. If 'a' is '0', the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f'

Example:
```
BTG     PORTC,  4
```
Before Instruction:
```
PORTC  =   0111 0101 [0x75]
```
After Instruction:
```
PORTC  =   0110 0101 [0x65]
```

BOV **Branch if Overflow**

Syntax: [*label*] BOV n

Operands: $-128 \le n \le 127$

Operation: if Overflow bit is '1',
$(PC) + 2 + 2n \rightarrow PC$

Status Affected: None

Encoding:

1110	0100	nnnn	nnnn

Description: If the Overflow bit is '1', then the program will branch.
The 2's complement number, '2n', is added to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is then a two-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:
If Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	Write to PC
No operation	No operation	No operation	No operation

If No Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	No operation

Example:
```
HERE    BOV   JUMP
```
Before Instruction
```
PC          =   address (HERE)
```
After Instruction
```
If Overflow =   1;
    PC      =   address (JUMP)
If Overflow =   0;
    PC      =   address (HERE + 2)
```

GOTO **Unconditional Branch**

Syntax: [*label*] GOTO k

Operands: $0 \le k \le 1048575$

Operation: $k \rightarrow PC<20:1>$

Status Affected: None

Encoding:

1st word (k<7:0>)	1110	1111	k_7kkk	$kkkk_0$
2nd word(k<19:8>)	1111	$k_{19}kkk$	kkkk	$kkkk_8$

Description: GOTO allows an unconditional branch anywhere within entire 2-Mbyte memory range. The 20-bit value, 'k', is loaded into PC<20:1>. GOTO is always a two-cycle instruction.

Words: 2

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'<7:0>,	No operation	Read literal 'k'<19:8>, Write to PC
No operation	No operation	No operation	No operation

Example: GOTO THERE

After Instruction
PC = Address (THERE)

INCF **Increment f**

Syntax: [*label*] INCF f [,d [,a]]

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) + 1 → dest

Status Affected: C, DC, N, OV, Z

Encoding:

0010	10da	ffff	ffff

Description: The contents of register, 'f', are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register, 'f'. If 'a' is '0', the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: INCF CNT,

Before Instruction
CNT = 0xFF
Z = 0
C = ?
DC = ?

After Instruction
CNT = 0x00
Z = 1
C = 1
DC = 1

RETFIE **Return from Interrupt**

Syntax: [*label*] RETFIE [s]

Operands: s ∈ [0,1]

Operation: (TOS) → PC,
1 → GIE/GIEH or PEIE/GIEL;
if s = 1:
(WS) → W,
(STATUSS) → STATUS,
(BSRS) → BSR,
PCLATU, PCLATH are unchanged

Status Affected: GIE/GIEH, PEIE/GIEL.

Encoding:

0000	0000	0001	000s

Description: Return from interrupt. Stack is popped and Top-of-Stack (TOS) is loaded into the PC. Interrupts are enabled by setting either the high or low-priority global interrupt enable bit. If 's' = 1, the contents of the shadow registers, WS, STATUSS and BSRS, are loaded into their corresponding registers, W, STATUS and BSR. If 's' = 0, no update of these registers occurs.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	No operation	POP PC from stack Set GIEH or GIEL
No operation	No operation	No operation	No operation

Example: RETFIE 1

After Interrupt
PC = TOS
W = WS
BSR = BSRS
STATUS = STATUSS
GIE/GIEH, PEIE/GIEL = 1

RETLW **Return Literal to W**

Syntax: [*label*] RETLW k

Operands: 0 ≤ k ≤ 255

Operation: k → W,
(TOS) → PC,
PCLATU, PCLATH are unchanged

Status Affected: None

Encoding:

0000	1100	kkkk	kkkk

Description: W is loaded with the 8-bit literal, 'k'. The program counter is loaded from the top of the stack (the return address). The high address latch (PCLATH) remains unchanged.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	POP PC from stack, Write to W
No operation	No operation	No operation	No operation

Example:

```
    CALL TABLE ; W contains table
               ; offset value
               ; W now has
               ; table value
    :
TABLE
    ADDWF PCL  ; W = offset
    RETLW k0   ; Begin table
    RETLW k1   ;
    :
    :
    RETLW kn   ; End of table
```

Before Instruction
W = 0x07
After Instruction
W = value of kn

26.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -55°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{MCLR}$, and RA4) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** ..... 0V to +13.25V
Voltage on RA4 with respect to Vss ..... 0V to +8.5V
Total power dissipation **(Note 1)** 1.0W
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin ..... 250 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports ..... 200 mA

Note 1: Power dissipation is calculated as follows:
$P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

2: Voltage spikes below V_{SS} at the $\overline{MCLR}/V_{PP}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}/V_{PP}$ pin, rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 26-16: I²C™ BUS DATA REQUIREMENTS (SLAVE MODE)

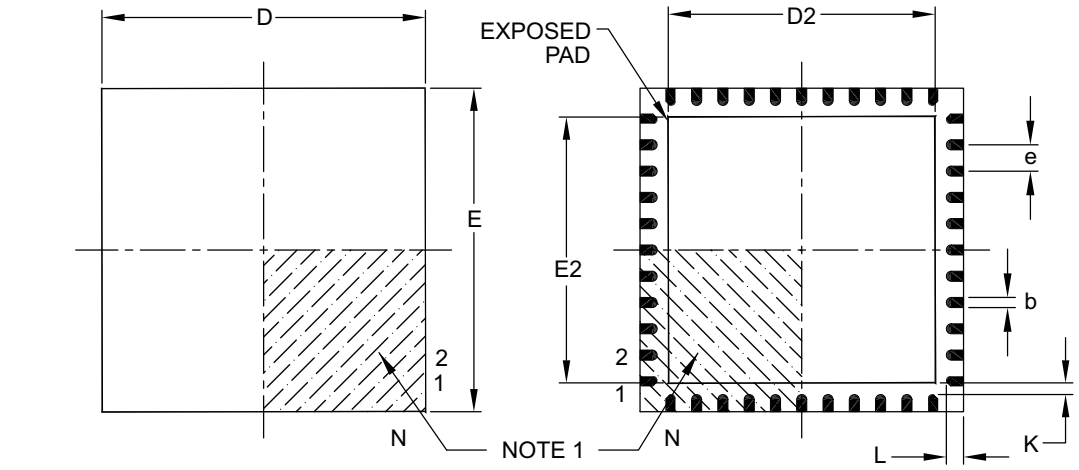
Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	4.0	—	μs	PIC18FXX31 must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	μs	PIC18FXX31 must operate at a minimum of 10 MHz
			SSP module	1.5 TCY	—		
101	TLOW	Clock Low Time	100 kHz mode	4.7	—	μs	PIC18FXX31 must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	μs	PIC18FXX31 must operate at a minimum of 10 MHz
			SSP Module	1.5 TCY	—		
102	TR	SDA and SCL Rise Time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	CB is specified to be from 10 to 400 pF
103	TF	SDA and SCL Fall Time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	CB is specified to be from 10 to 400 pF
90	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	μs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	μs	
91	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	μs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	μs	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	μs	
			400 kHz mode	0.6	—	μs	
109	TAA	Output Valid From Clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
D102	CB	Bus Capacitive Loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

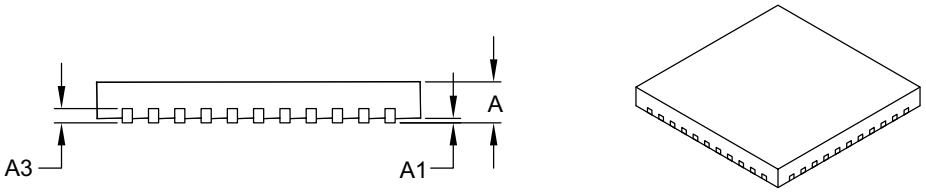
2: A Fast mode I²C bus device can be used in a Standard mode I²C bus system, but the requirement, TSU:DAT ≥ 250 ns, must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line,. TR max. + TSU:DAT = 1000 + 250 = 1250 ns (according to the Standard mode I²C bus specification), before the SCL line is released.

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW **BOTTOM VIEW**



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.30	6.45	6.80
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.30	6.45	6.80
Contact Width	b	0.25	0.30	0.38
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103B